



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Drill, C. et al.
Serial No. : 08/824,633 Group Art Unit : 3724
Filed : 03/27/97 Examiner : Rachuba, M.
For : A CUSTOMIZED POLISHING PAD FOR SELECTIVE PROCESS
PERFORMANCE DURING CHEMICAL MECHANICAL
POLISHING

RECEIVED

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TC 3700 MAIL ROOM

AMENDMENT AND RESPONSE

Assistant Commissioner for Patents & Trademarks
Washington, D.C. 20231

Sir:

In response to the Office Action mailed 03/08/01, please amend the above-referenced Application as follows:

IN THE CLAIMS

Sub E
Please add the following new Claim:

-- 21. (New) A process specific polishing pad having a plurality of regions configured to implement different polishing hardness on the surface of a wafer, the process specific polishing pad comprising:

a polishing pad having an overlying layer, said overlying layer being uniform and homogenous across a polishing surface of said overlying layer, said polishing surface adapted to frictionally contact a wafer as said wafer is polished in said wafer polishing machine; and

said polishing surface having a plurality of regions, each of said plurality of regions configured to achieve a specific hardness effect by using a respective